

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY COPPER ALLOY TO OBTAIN A
LOW RESISTANCE AND LARGE GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Ori Nadav

Art Unit: 2811

Confirmation 7882
Number:

AMENDMENT AND REPLY UNDER 37 CFR 1.111

Mail Stop AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This communication is responsive to the Non-Final Office Action dated June 12, 2009,
concerning the above-referenced patent application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2
of this document.

Remarks/Arguments begin on page 7 of this document.

Please amend the application as follows: